



COOLANT MANAGEMENT

AND DEBRIS REMOVAL SYSTEMS

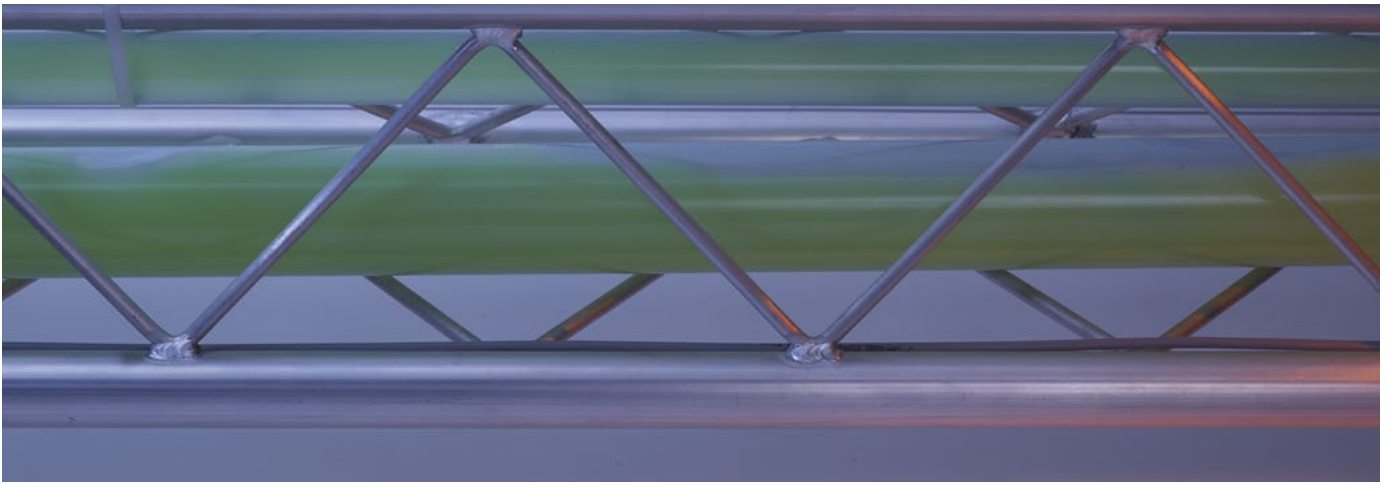
COOLANT MANAGEMENT

Machining coolants play a critical role in high volume lens manufacturing. Monitoring, managing, and recycling fluids from lens production improves productivity, saves money through optimized tool life, and reduces machine downtime, coolant concentrate purchases and minimizes waste and disposal costs. Coolant management and chip removal systems by Bazell Technologies®, are available for a range of production scenarios, from a single line to mass manufacturing. The systems guarantee optimal lubrication for increased machining speeds, as well as a safe, clean working environment for continuous, around-the-clock production of all lens format.

These systems provide:

- Accurate coolant pressure and flow control for effective debris evacuation from the cutting chamber
- Industrial grade PLC controls with intuitive touchscreen interface
- Heavy gauge, self-cleaning stainless steel reservoir with positive counter current flow eliminating surface and bottom debris accumulation
- All are optimized for the most modern processes (Digital/ART)





HC2

Automated coolant cleaning system for up to two lens generators with any mixture of organic lens materials. Specifically designed for Satisloh's VFT-orbit-2, the HC2 can process the debris of 220 lenses per hour. Use with Integrated or Standard Pump Station to maximize production space by relocating the coolant cleaning system to a remote location in your facility.

HC3/HC6/HC6 PLUS

Automated coolant cleaning system for organic materials. Seamlessly integrates with Pump Stations, Chip Separators, or Compactor Assemblies. Designed for operation remote from generators for optimum use of surfacing laboratory space. HC3 supports up to three generators; the HC6/HC6 Plus* is for mass manufacturing environments, supporting up to six generators.

* For high % volumes of CR39



HC2

Productivity:	Up to 220 PC/HI/CR lenses/hour
Power	208 V, 60 A, 60 Hz / 400 V, 60 A, 50 Hz
Dimensions (wxdxh)	1473 x 3454 x 2228 mm / 58 x 136 x 88 in
Weight	1252 kg / 2760 lbs
Air	5 bar @ 28 l/m / 75 psi @1SCFM
Water	2 bar / 30 psi

HC3

Productivity:	PC/HI: up to 300 lenses/hour CR: up to 200 lenses/hour
Power	208 V, 60 A, 60 Hz, 3 phase / 400 V, 60 A, 50 Hz, 3 phase
Dimensions (wxdxh)	1334 x 2729 x 2127 cm / 53 x 108 x 84 in
Weight	943 kg / 2079 lbs
Air	5 bar @ 28 l/m / 75 psi @1SCFM
Water	2 bar / 30 psi



FEATURES + BENEFITS

- Achieve maximum productivity from generator
- Minimized routine cleaning: no generator interruptions during production
- Centrifuge self-cleans without stopping production
- Automatic chip separation or compacting
- Tanks with anti-sedimentation system substantially reduce cleaning
- UL508A construction
- Continuous high pressure fluid delivery to generator
- Automatic water makeup, coolant mixing, and additive dosing
- Simple alarm display with downloadable data logs
- Intuitive operator interface
- Automatically maintains both coolant levels and proportions



HC6

PC/Hi: up to 600 lenses/hour
CR: up to 400 lenses/hour

480 V, 100 A, 60 Hz, 3 phase / 400 V, 100 A, 50 Hz, 3 phase

3300 x 3400 x 2728 cm / 134 x 130 x 107 in

2730 kg / 6000 lbs

5 bar @ 57 l/m / 75 psi @ 2 SCFM

2 bar / 30 psi

HC6 Plus

Up to 600 PC/Hi/CR lenses/hour

480 V, 100 A, 60 Hz, 3 phase / 400 V, 100 A, 50 Hz, 3 phase

3472 x 3627 x 2885 cm / 137 x 143 x 114 in

3265 kg / 7200 lbs

5 bar @ 85 l/m / 75 psi @ 3SCFM

2 bar / 30 psi



Integrated Pump Station / Pump Station



Chip Separator



WEIMA Briquette press for swarf management

PERIPHERAL EQUIPMENT

Integrated and Standard Pump Station

Transport all fluids and debris through an overhead pipeline to a single collection point (Chip Separator or Chip Compactor system), eliminating the need for tanks and debris bins in the surfacing area. With the smallest footprint possible, it allows positioning between conveyors.

Chip Separator

Traps and separates fluids mixed with chip and tape debris, maximizing water and coolant recovery and reuse. Chip debris automatically discharges to debris bins or conveyors supplied by the customer when used with a briquetter. For high volume of CR39 and HI.

Available in two sizes:

- Chip Separator Assembly Dual
- Chip Separator Assembly Triple

Chip Compactor

Collects and compacts chip and tape debris from surfacing. Chip debris automatically discharges to debris bins or conveyor belt supplied by the customer. The compacted material density varies by lens material. The Chip Compactor is designed to provide exceptional machine performance with the smallest footprint possible for best use of production floor space.

For high volume of PC, Trivex, and HI.

Available in two sizes:

- Double Chip Compactor
- Triple Chip Compactor

WEIMA Briquette Press

The WEIMA Briquette press is an ideal complement to the HC6 Coolant Management Systems for unrivaled swarf management. The volume of input material can be reduced by up to 12.5:1. Reduces waste-material handling and labor, saves money on waste disposal costs, and recovers up to 50% more coolant. Designed to work with one or two HC6 Systems, depending upon model.

The WEIMA Briquette press is available in two configurations.

- TH800 Vario works with two HC6/Plus Systems
- TH600 Vario works with one HC6/Plus System

Lens debris is automatically transported from Chip Separators to the WEIMA Briquette press. Recovered coolant from the briquetting process is pumped back to the HC6 tank(s).

TECHNICAL INFORMATION

	Power	Dimensions (wxdxh)	Weight	Air
Integrated Pump Station	Provided by VFT-orbit-2	310 x 1170 x 824 mm 13 x 43 x 33 in	80 kg/176 lbs	4,2 bar @ 28 l/m 60 psi @ 1 SCFM
Standard Pump Station	208 V, 15 A, 60 Hz 400 V, 15 A, 50 Hz	310 x 1170 x 824 mm 13 x 43 x 33 in	80 kg/176 lbs	4,2 bar @ 28 l/m 60 psi @ 1 SCFM
Chip Separator Assembly Dual	Provided by Microseparator system	862 x 1087 x 1404 mm 34 x 43 x 56 in	172 kg/378 lbs	Provided by Microseparator System
Chip Separator Assembly Triple	Provided by Microseparator system	1159 x 1096 x 1404 mm 46 x 44 x 56 in	218 kg/480 lbs	Provided by Microseparator System
Double Compactor	Provided by Microseparator system	697 x 1119 x 1793 mm 28 x 45 x 71 in	281 kg/620 lbs	Provided by Microseparator System
Triple Compactor	Provided by Microseparator system	999 x 1119 x 1793 mm 40 x 45 x 71 in	332 kg/732 lbs	Provided by Microseparator System
WEIMA TH600 Vario Briquette press	460 V, 35 A, 60 Hz 400 V, 40 A, 50 Hz	2300 x 2118 x 1553 mm 90 x 84 x 62 in	1000 kg/2205 lbs	5,2 bar @ 56 l/m 75 psi @ 2 SCFM
WEIMA TH800 Vario Briquette press	460 V, 80 A, 60 Hz 400 V, 80 A, 50 Hz	2300 x 2069 x 2088 mm 90 x 81 x 82 inch	1100 kg/2430 lbs	5,2 bar @ 56 l/m 75 psi @ 2 SCFM

CONFIGURATIONS

modular customized to your lab specific needs

	HC2	HC3	HC6	HC6 Plus
Generators supported	2	Up to 3	Up to 6	Up to 6
Pump station required	1 per generator	1 per generator	1 per generator	1 per generator
Chip Compactor or Chip Separator with tank	Chip Separator included	1 per generator	1 per generator	1 per generator
WEIMA TH600 Vario Briquette press	-	One per 2 HC3	One per HC6	One per HC6 Plus
WEIMA TH800 Vario Briquette press	-	-	One per 2 HC6	One per 2 HC6 Plus

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